



- ☐ Drafts
- ☐ Pending
- ☒ Active
 - L1: (1) ("6709695").PN.
 - L2: (1) ("6673651").PN.
 - L3: (1) ("5148265").PN.
 - L4: (1) ("5148266").PN.
 - L5: (1) ("5679977").PN.
 - L6: (1) ("5347159").PN.
 - L7: (1) ("4941033").PN.
 - L8: (1) ("5659952").PN.
 - L9: (1) ("5706174").PN.
 - L10: (1) ("6169328").PN.
 - L11: (1) ("5646446").PN.
 - L12: (1) ("5455740").PN.
 - L13: (1) ("5046238").PN.
 - L14: (1) ("5222014").PN.
 - L15: (1) ("5440171").PN.
 - L16: (1) ("4982265").PN.
 - L17: (22835) microelectronic
 - L18: (332) 17 and (substrate and first near microel
- ☐ Failed
- ☐ Saved
- ☐ Favorites
- ☐ Tagged (0)
- ☐ UDC
- ☐ Queue
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☐ Exact

Default operator: OR

☒ Highlight all hit items only

17 and (substrate and first near microelectronic)

☒ BRS form ☒ SAR form ☐ Image ☐ Text ☐ HTML

	U	I	Document ID	Issue Date	Pages	Title	Current OR	Current XRef	
1	<input type="checkbox"/>	<input type="checkbox"/>	US 20050040540 A1	20050224	18	Microelectronic assemblies with springs	257/778	257/774; 257/784; 257/837	<input type="checkbox"/>
2	<input type="checkbox"/>	<input type="checkbox"/>	US 20050026415 A1	20050203	14	Fabrication of stacked microelectronic devices	438/612	257/685	
3	<input type="checkbox"/>	<input type="checkbox"/>	US 20050026395 A1	20050203	14	Fabrication of stacked microelectronic devices	438/460	438/113	
4	<input type="checkbox"/>	<input type="checkbox"/>	US 20050026325 A1	20050203	14	Packaged microelectronic components	438/107	257/678	
5	<input type="checkbox"/>	<input type="checkbox"/>	US 20050023655 A1	20050203	16	Packaged microelectronic devices and methods of forming same	257/676	438/123	
6	<input type="checkbox"/>	<input type="checkbox"/>	US 20050019988 A1	20050127	14	Method and apparatus for attaching microelectronic substrates and support members	438/125	438/617	
7	<input type="checkbox"/>	<input type="checkbox"/>	US 20050019984 A1	20050127	12	Multiple substrate microelectronic devices and methods of manufacture	438/109		
8	<input type="checkbox"/>	<input type="checkbox"/>	US 20050012185 A1	20050120	19	Microelectronic component assemblies employing lead frames having reduced-thickness inner lengths	257/666		
9	<input type="checkbox"/>	<input type="checkbox"/>	US 20050007736 A1	20050113	4	Microelectronic package within cylindrical housing	361/688		
10	<input type="checkbox"/>	<input type="checkbox"/>	US 20050066787 A1	20050113	9	Substrate-less microelectronic package	257/777	257/686	
11	<input type="checkbox"/>	<input type="checkbox"/>	US 20040262733 A1	20041230	10	Scalable microelectronic package using conductive fibers	257/666	438/109	